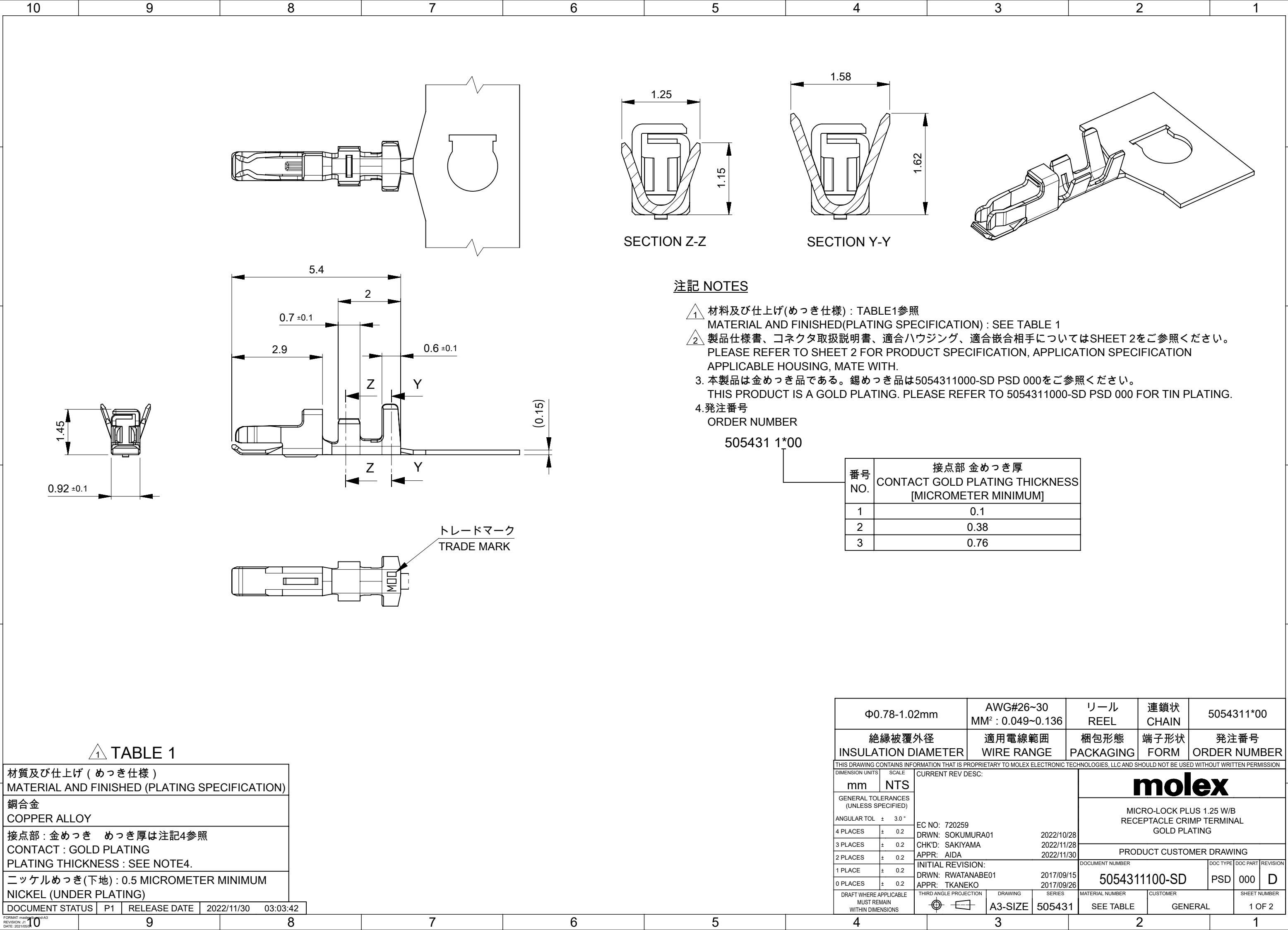




注記 NOTES

- 1 材料及び仕上げ(めっき仕様) : TABLE1参照
MATERIAL AND FINISHED(PLATING SPECIFICATION) : SEE TABLE 1
- 2 製品仕様書、コネクタ取扱説明書、適合ハウジング、適合嵌合相手についてはSHEET 2をご参照ください。
PLEASE REFER TO SHEET 2 FOR PRODUCT SPECIFICATION, APPLICATION SPECIFICATION APPLICABLE HOUSING, MATE WITH.
3. 本製品は金めっき品である。錫めっき品は5054311000-SD PSD 000をご参照ください。
THIS PRODUCT IS A GOLD PLATING. PLEASE REFER TO 5054311000-SD PSD 000 FOR TIN PLATING.
4. 発注番号
ORDER NUMBER

505431 1*00

番号 NO.	接点部 金めっき厚 CONTACT GOLD PLATING THICKNESS [MICROMETER MINIMUM]
1	0.1
2	0.38
3	0.76

1 TABLE 1

材質及び仕上げ (めっき仕様) MATERIAL AND FINISHED (PLATING SPECIFICATION)				
銅合金 COPPER ALLOY				
接点部 : 金めっき めっき厚は注記4参照 CONTACT : GOLD PLATING PLATING THICKNESS : SEE NOTE4.				
ニッケルめっき(下地) : 0.5 MICROMETER MINIMUM NICKEL (UNDER PLATING)				
DOCUMENT STATUS	P1	RELEASE DATE	2022/11/30	03:03:42

Φ0.78-1.02mm		AWG#26~30 MM ² : 0.049~0.136	リール REEL	連鎖状 CHAIN	5054311*00
絶縁被覆外径 INSULATION DIAMETER		適用電線範囲 WIRE RANGE	梱包形態 PACKAGING	端子形状 FORM	発注番号 ORDER NUMBER
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			CURRENT REV DESC:		
DIMENSION UNITS mm		SCALE NTS	molex MICRO-LOCK PLUS 1.25 W/B RECEPTACLE CRIMP TERMINAL GOLD PLATING		
GENERAL TOLERANCES (UNLESS SPECIFIED)					
ANGULAR TOL		± 3.0 °			
4 PLACES		± 0.2			
3 PLACES		± 0.2	PRODUCT CUSTOMER DRAWING		
2 PLACES		± 0.2	INITIAL REVISION:		
1 PLACE		± 0.2	DRWN: RWATANABE01 2017/09/15		
0 PLACES		± 0.2	APPR: TKANEKO 2017/09/26		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING A3-SIZE	SERIES 505431	DOCUMENT NUMBER 5054311100-SD
				MATERIAL NUMBER SEE TABLE	CUSTOMER GENERAL
					SHEET NUMBER 1 OF 2

